L Numb r	Hits	S ar h Text	DB	Time stamp
-	2	("6228687").PN.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/08/19 20:40
-	2	897332.ap.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/08/19 20:47
-	174646	shear!	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/08/19 20:56
-	2116372	edge	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/08/19 20:48
-	704	shear! adj edge	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/08/19 20:48
-	2953670	contact	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/08/19 20:48
-	51	(shear! adj edge) with contact	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/08/19 20:49
-	1199264	@ad>20010701 @rlad>20010701 @pt1d>20010701	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/08/19 20:50
-	46	((shear! adj edge) with contact) not (@ad>20010701 @rlad>20010701 @pt1d>20010701)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/08/19 21:18
-	418036	sharp sharpened	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/08/19 20:56

	122467	r und! rounded	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/08/19 20:56
	0	((shear! adj edge) with (sharp sharpened)) and ((shear! adj edge) with (round! rounded))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/08/19 20:57
	3	(shear! adj edge) with (round! rounded)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/08/19 20:57
	590474	smooth	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/08/19 20:58
	6	(shear! adj edge) with smooth	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/08/19 20:58
	33	(shear! adj edge) with (sharp sharpened)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/08/19 21:13
	1618732	semiconductor integrated adj circuit ic	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/08/19 21:00
	12	(shear! adj edge) and (semiconductor integrated adj circuit ic)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/08/19 21:01
	9	((shear! adj edge) and (semiconductor integrated adj circuit ic)) not (@ad>20010701 @rlad>20010701 @pt1d>20010701)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/08/19 21:02
	3371281	circuit$	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/08/19 21:03

- ..	75	(shear! adj edge) and circuit$	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/08/19 21:03
-	65	((shear! adj edge) and circuit$) n t ((((shear! adj edge) and (semiconductor integrated adj circuit ic)) not (@ad>20010701 @rlad>20010701 @pt1d>20010701)) (@ad>20010701 @rlad>20010701 @pt1d>20010701))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/08/19 21:03
-	1	2000-278808.NRAN.	DERWENT	2003/08/19 21:09
-	1	(inter adj con).pa.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/08/19 21:19
-	1	(inter adj con).as.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/08/19 21:19
-	0	intercon.pa.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/08/19 21:20
-	1	intercon.as. and shear!	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/08/19 21:20
-	72	intercon.as.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/08/19 21:35
-	47359	burr	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/08/19 21:36
-	1	yazaki.as. and burr	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/08/19 21:38
-	31907	yazaki.as.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/08/19 21:42

~ ··	47359	burr	USPAT; US-P PUB; EPO; JPO; DERWENT; IBM_TDB	2003/08/19 21:42
-	78	yazaki.as. and burr	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/08/19 21:42
-	68	(yazaki.as. and burr) not (@ad>20010701 @rlad>20010701 @pt1d>20010701)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/08/19 21:54
-	8	("2748452" | "2845606" | "3577119" | "3795889" | "3813645" | "4466689" | "4712299" | "5519170").PN.	USPAT	2003/08/19 21:50
-	0	6000976.URPN.	USPAT	2003/08/19 21:51
-	0	6000976.URPN.	USPAT	2003/08/19 21:52
-	4	("3937545" | "4717356" | "4772231" | "4921437").PN.	USPAT	2003/08/19 21:52
-	5	5545062.URPN.	USPAT	2003/08/19 21:53
-	7	(shear! adj edge) with burr	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/08/19 21:54